

Silicon Carbide JFET

CoolSiC™ JFET 750 V J1 in QDPAK

The CoolSiC™ junction-gate field-effect transistor (JFET) addresses the requirements of protection circuits in solid-state power distribution. It offers low on-state resistance and high ruggedness; additionally, the package enables fully automated assembly and flexible cooling path design.

Features

- Low on-state resistance $R_{DS(on)}$
- High-current avalanche ruggedness
- Surge current ruggedness
- Overload operation up to 200°C
- Compatible with automated assembly

Benefits

- Unique combination of high performance, high reliability and ease of use
- Ease of use and integration
- Higher robustness and system reliability
- Efficiency improvement
- Reduced system size leading to higher power density

Potential applications

- Solid-state circuit breaker
- Solid state relay
- Battery disconnect switch

Product validation

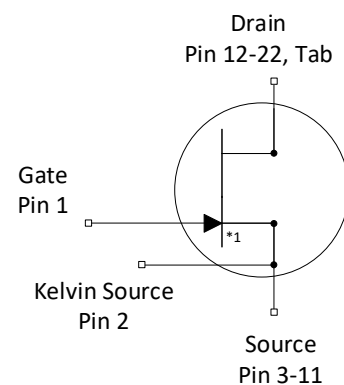
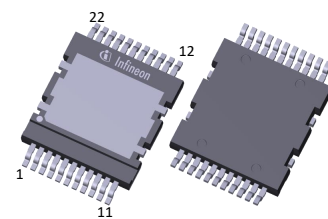
Qualified according to relevant JEDEC tests.

Please note: The source and driver source pins are not exchangeable. Their exchange might lead to malfunction.

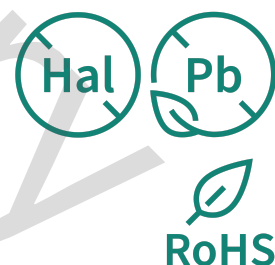
Table 1 Key performance parameters

Parameter	Value	Unit
V_{DS} over full $T_{j,range}$	750	V
$R_{DS(on),typ}$	2.19	mΩ
I_{DM}	1283	A
i^2t	tbd	A ² s
I_{AS}	519	A

PG-HDSOP-22



*1: Internal gate diode



Part number	Package	Marking	Related links
IJCQ75RM22J1	PG-HDSOP-22	75RM22J1	see Appendix A

Table of contents

Description	1
Maximum ratings and recommendations	3
Thermal characteristics	4
Electrical characteristics	5
Electrical characteristics diagrams	7
Test circuits	11
Package outlines	12
Appendix A	15
Revision history	16
Trademarks	17
Disclaimer	17

1 Maximum ratings and recommendations

Note: for optimum lifetime and reliability, Infineon recommends operating conditions that do not exceed 70% of the maximum rated V_{DS} stated in this datasheet. For applications with higher applied blocking voltage it is required that the customer evaluates the impact of cosmic radiation effect in early design phase and contacts the Infineon sales office for the necessary technical support by Infineon.

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Drain-source voltage	V_{DS}	-	-	750	V	$V_{GS} = -18\text{ V}$, $T_j = -55^\circ\text{C}$ to 175°C
Continuous DC drain current ¹⁾	I_{DDC}	-	-	419	A	$T_c = 25^\circ\text{C}$, $V_{GS} = 2\text{ V}$
				346		$T_c = 105^\circ\text{C}$, $V_{GS} = 2\text{ V}$
Peak drain current	I_{DM}	-	-	1283	A	$T_c = 25^\circ\text{C}$, $V_{GS} = 2\text{ V}$, $V_{DS} = 5\text{ V}$, pulse width t_p limited by $T_{j,max}$
$i^2 t$ ²⁾	$\int i^2 dt$	-	-	tbd	A ² s	$V_{GS} = 2\text{ V}$, $T_j = 25^\circ\text{C}$, $t_p = 10\text{ ms}$ (sine half wave)
						$V_{GS} = 2\text{ V}$, $T_j = 25^\circ\text{C}$, $t_p = 30\text{ }\mu\text{s}$ (rectangular)
Avalanche energy, single pulse ³⁾	E_{AS}	-	-	135	mJ	$I_D = 519\text{ A}$, $V_{GS} = -18\text{ V}$, $L = 1\text{ }\mu\text{H}$, $T_j = 25^\circ\text{C}$
Avalanche current, single pulse	I_{AS}	-	-	519	A	$V_{DD} = 100\text{ V}$, $V_{GS} = -18\text{ V}$, $L = 1\text{ }\mu\text{H}$, $T_j = 25^\circ\text{C}$
JFET dv/dt ruggedness ²⁾	dv/dt	-	-	20	V/ns	$V_{DS} = 0 \dots 400\text{ V}$
Gate-source voltage	V_{GS}	-20	-	2.2	V	static
		-30	-	10		$I_{GF} = \text{tbd A}$, transient
Power dissipation	P_{tot}	-	-	1807	W	$T_c = 25^\circ\text{C}$
Storage temperature	T_{stg}	-55	-	150	$^\circ\text{C}$	-
Operating junction temperature	T_j			175		
Operating junction temperature extended	$T_{j,ext}$	-	-	200	$^\circ\text{C}$	Overload; cumulative max. 100 h and max. 5000 cycles with $\Delta T \leq 100\text{ K}$

¹⁾ Limited by $T_{j,max}$.

²⁾ Not subject to production test. Parameter verified by design/characterization.

³⁾ It is always recommended to use an external clamping element (e.g. MOV).

Table 3 Recommended operating conditions

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Gate-source voltage	V_{GS}	0	2	-	V	Turn-on
		-	-18			Turn-off
Drain-source voltage	V_{DS}	-	-	525	V	-

2 Thermal characteristics

Table 4 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case ⁴⁾	$R_{th(j-c)}$	-	0.059	0.083	K/W	-
Soldering temperature	T_{sold}	-	-	260	°C	Reflow soldering (MSL1 according to JEDEC J-STD-020)

⁴⁾ Not subject to production test. Parameter verified by design.

3 Electrical characteristics

Table 5 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage ⁵⁾	$V_{(BR)DSX}$	775	-	-	V	$V_{GS} = -18\text{ V}$, $I_D = 4.02\text{ mA}$, $T_j = 25^\circ\text{C}$
Gate-source threshold voltage	$V_{GS(th)}$	-7	-5.3	-3	V	$V_{DS} = 1\text{ V}$; $I_D = 6.0\text{ mA}$, $T_j = 25^\circ\text{C}$
		-8.6	-7	-4.4		$V_{DS} = 525\text{ V}$; $I_D = 6.0\text{ mA}$, $T_j = 25^\circ\text{C}$
Drain cut-off current	$I_{D(off)}$	-	2.35	221	μA	$V_{DS} = 750\text{ V}$, $V_{GS} = -18\text{ V}$, $T_j = 25^\circ\text{C}$
			10.94	-		$V_{DS} = 750\text{ V}$, $V_{GS} = -18\text{ V}$, $T_j = 175^\circ\text{C}$
			0.14	4.42		$V_{DS} = 525\text{ V}$, $V_{GS} = -18\text{ V}$, $T_j = 25^\circ\text{C}$
			0.55	-		$V_{DS} = 525\text{ V}$, $V_{GS} = -18\text{ V}$, $T_j = 175^\circ\text{C}$
Reverse gate current	I_{GSS}	-	0.12	13.3	μA	$V_{GS} = -18\text{ V}$, $T_j = 25^\circ\text{C}$
			1.25	-		$V_{GS} = -18\text{ V}$, $T_j = 175^\circ\text{C}$
Forward gate current	I_{GF}	-	35	-	μA	$V_{GS} = 2\text{ V}$, $T_j = 25^\circ\text{C}$
Drain-source on-state resistance	$R_{DS(on)}$	-	2.47	-	m Ω	$V_{GS} = 0\text{ V}$, $I_D = 40.2\text{ A}$, $T_j = 25^\circ\text{C}$
			2.19	-		$V_{GS} = 2\text{ V}$, $I_D = 40.2\text{ A}$, $T_j = 25^\circ\text{C}$
			3.71	-		$V_{GS} = 0\text{ V}$, $I_D = 40.2\text{ A}$, $T_j = 105^\circ\text{C}$
			3.29	-		$V_{GS} = 2\text{ V}$, $I_D = 40.2\text{ A}$, $T_j = 105^\circ\text{C}$
			4.77	6.20		$V_{GS} = 0\text{ V}$, $I_D = 40.2\text{ A}$, $T_j = 150^\circ\text{C}$
			4.15	5.39		$V_{GS} = 2\text{ V}$, $I_D = 40.2\text{ A}$, $T_j = 150^\circ\text{C}$
Internal gate resistance	$R_{G,int}$	-	0.5	-	Ω	$f = 1\text{ MHz}$

⁵⁾ Provided as measure of robustness under abnormal operating conditions and not recommended for normal operation.

Table 6 Dynamic characteristics

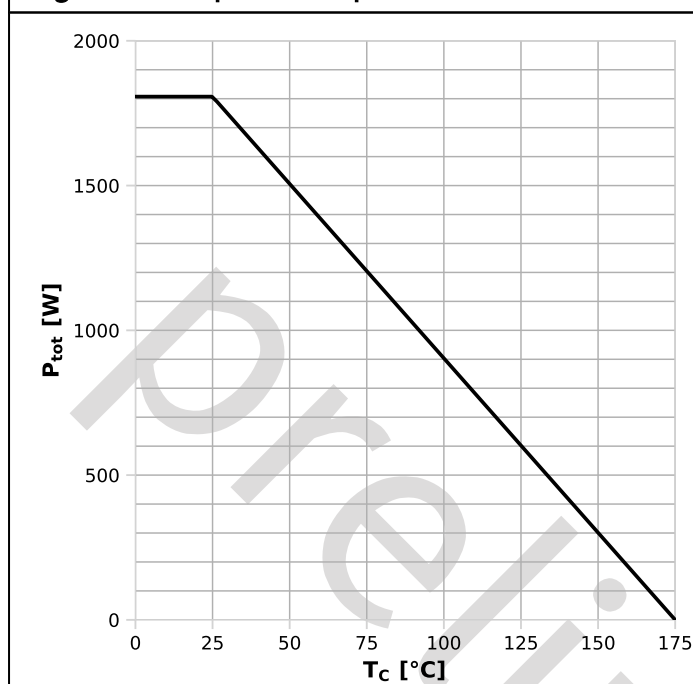
Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	7471	-	pF	$V_{GS} = -18\text{ V}$, $V_{DS} = 525\text{ V}$, $f = 250\text{ kHz}$, $T_j = 25^\circ\text{C}$
Reverse transfer capacitance	C_{rss}		655			
Output capacitance	C_{oss}		664			
Turn-on delay time	$t_{d(on)}$	-	tbd	-	ns	$V_{DD} = 525\text{ V}$, $V_{GS} = -18/2\text{ V}$, $I_D = 40.2\text{ A}$, $R_{G,ext} = 1.8\text{ }\Omega$ $T_j = 25^\circ\text{C}$; tested in double pulse setup with SiC Diode for free wheeling phase
Rise time	t_r				ns	
Turn-off delay time	$t_{d(off)}$				ns	
Fall time	t_f				ns	
Turn-ON switching losses	E_{on}				μJ	
Turn-OFF switching losses	E_{off}				μJ	
Total switching losses	E_{tot}				μJ	

Table 7 Gate charge characteristics

Parameter	Symbol	Values			Unit	Note / Test condition
		Min.	Typ.	Max.		
Gate-source charge below plateau	$Q_{GS(pl)}$	-	99	-	nC	$V_{DD} = 525\text{ V}$, $I_D = 40.2\text{ A}$, $V_{GS} = -18/2\text{ V}$, $T_j = 25^\circ\text{C}$
Gate-drain charge	Q_{GD}		547			
Total gate charge	Q_G		979			

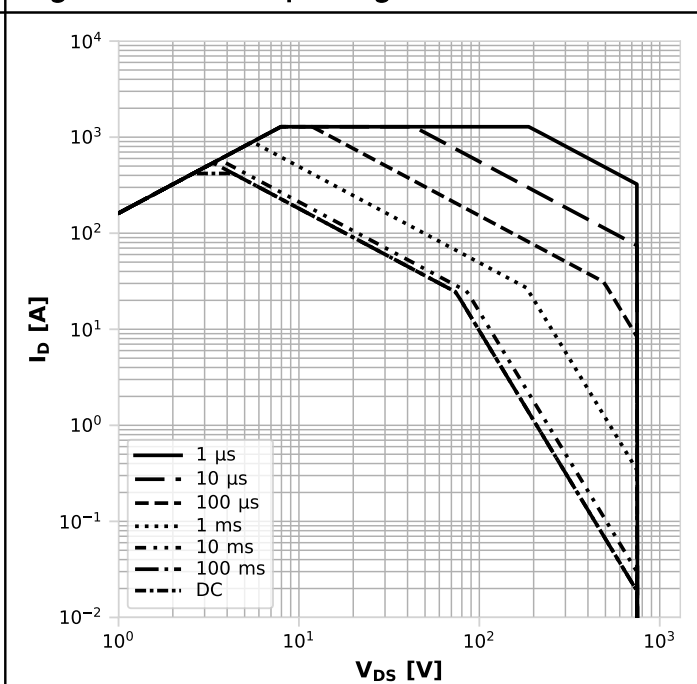
4 Electrical characteristics diagrams

Diagram 1: Max. power dissipation



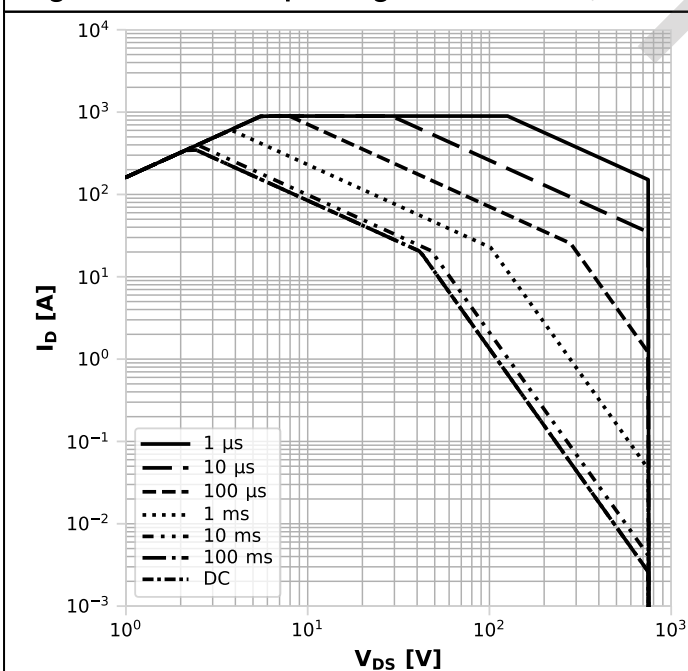
$$P_{tot}=f(T_c)$$

Diagram 2: Max. Safe operating area



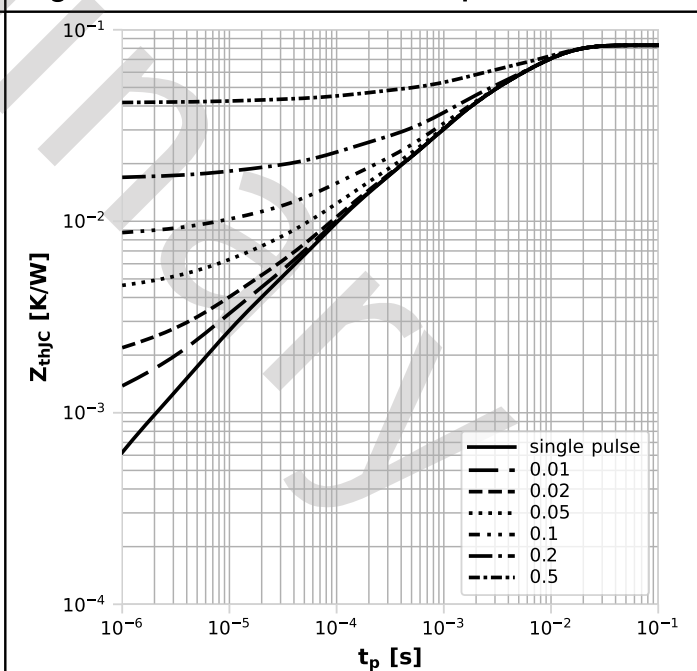
$$I_D=f(V_{DS}); T_c=25^\circ\text{C}; D=0; \text{parameter: } t_p$$

Diagram 3: Max. Safe operating area



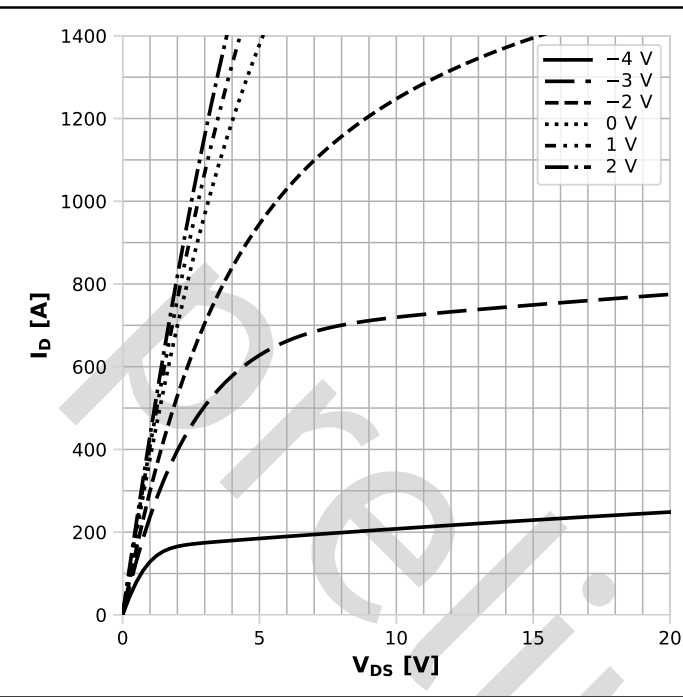
$$I_D=f(V_{DS}); T_c=105^\circ\text{C}; D=0; \text{parameter: } t_p$$

Diagram 4: Max. transient thermal impedance



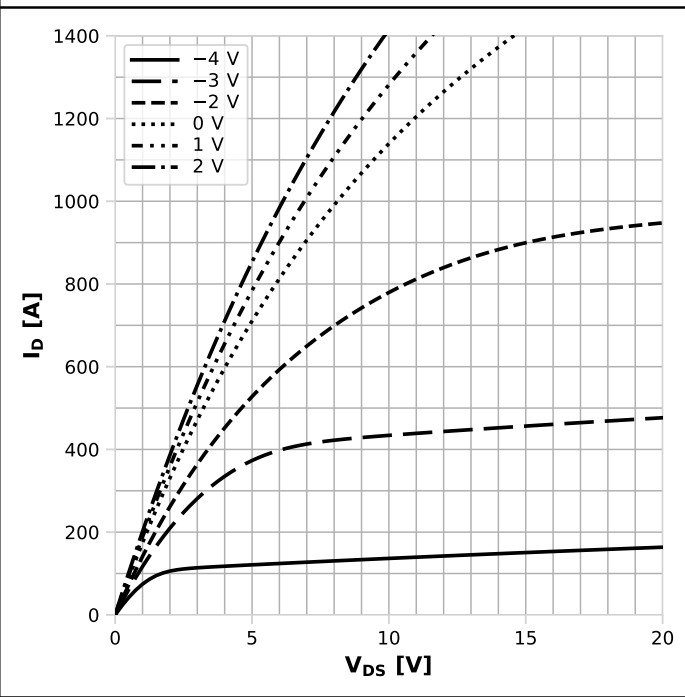
$$Z_{thJC}=f(t_p); \text{parameter: } D=t_p/T$$

Diagram 5: Typ. output characteristics



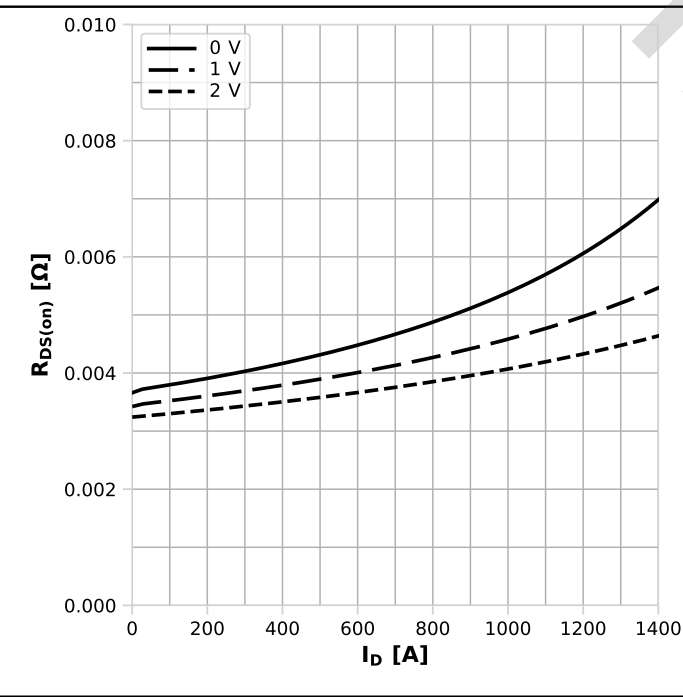
$I_D = f(V_{DS})$; $T_j = 25\text{ °C}$; parameter: V_{GS}

Diagram 6: Typ. output characteristics



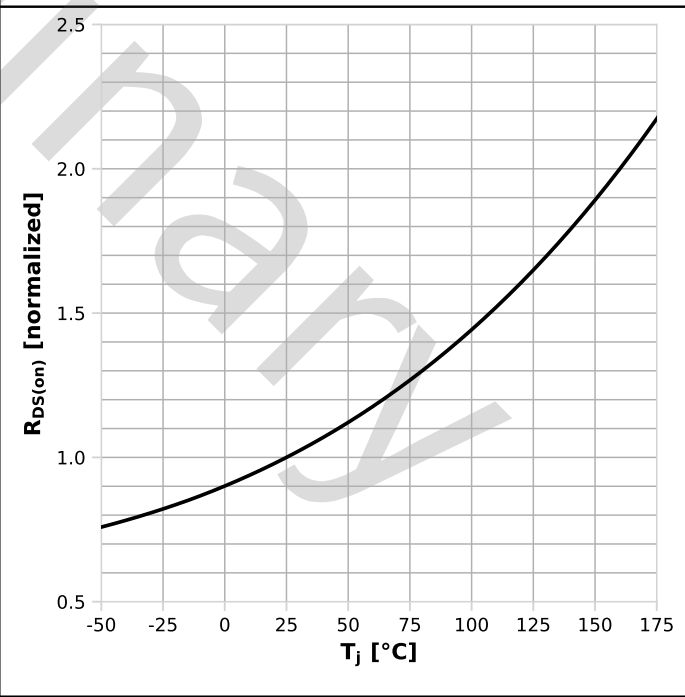
$I_D = f(V_{DS})$; $T_j = 175\text{ °C}$; parameter: V_{GS}

Diagram 7: Typ. drain-source on-state resistance



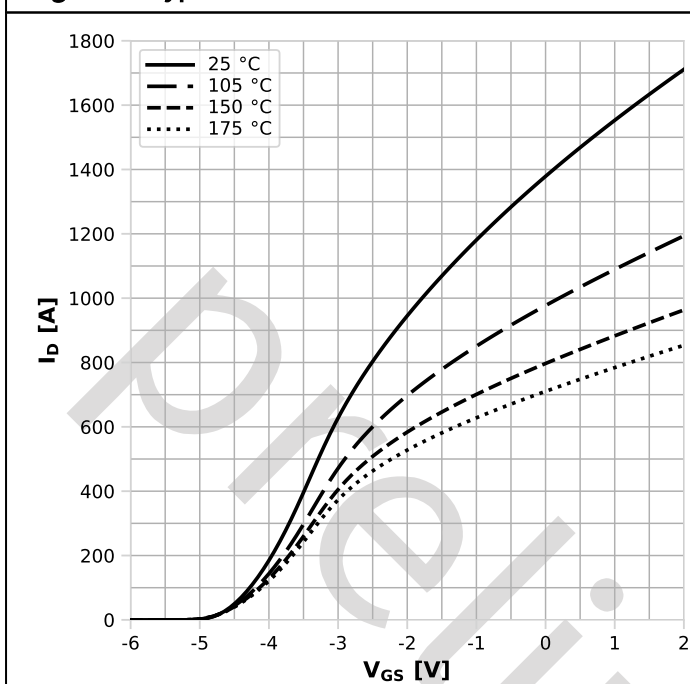
$R_{DS(on)} = f(I_D)$; $T_j = 105\text{ °C}$; parameter: V_{GS}

Diagram 8: Typ. drain-source on-state resistance



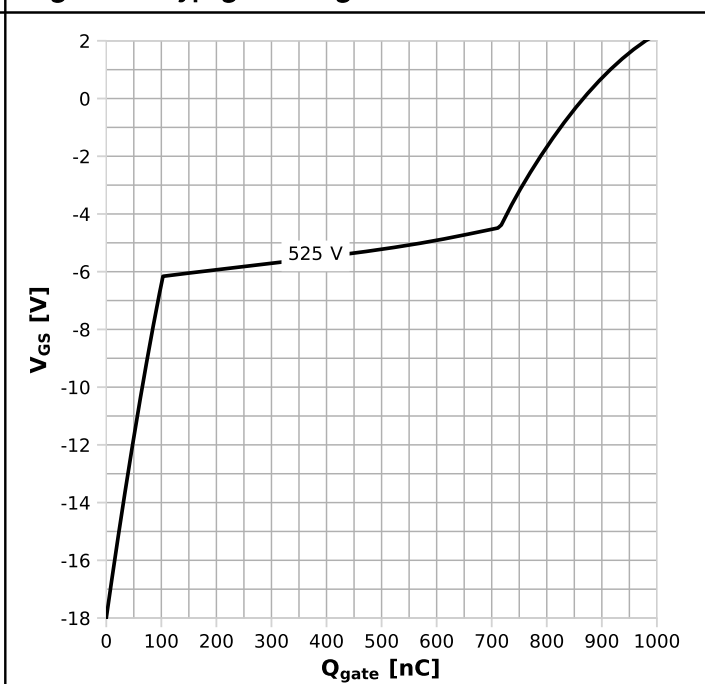
$R_{DS(on)} = f(T_j)$; $I_D = 40.2\text{ A}$; $V_{GS} = 2\text{ V}$

Diagram 9: Typ. transfer characteristics



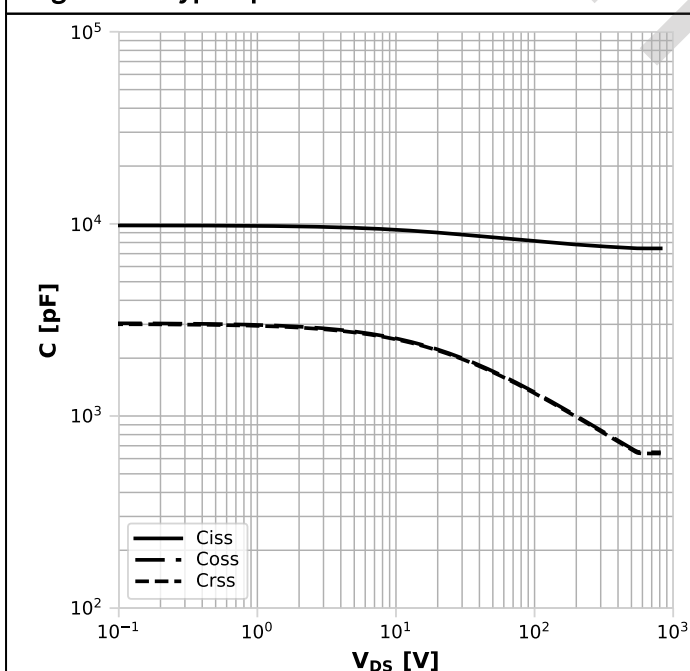
$I_D = f(V_{GS})$; $V_{DS} = 5 \text{ V}$; parameter: T_j

Diagram 10: Typ. gate charge



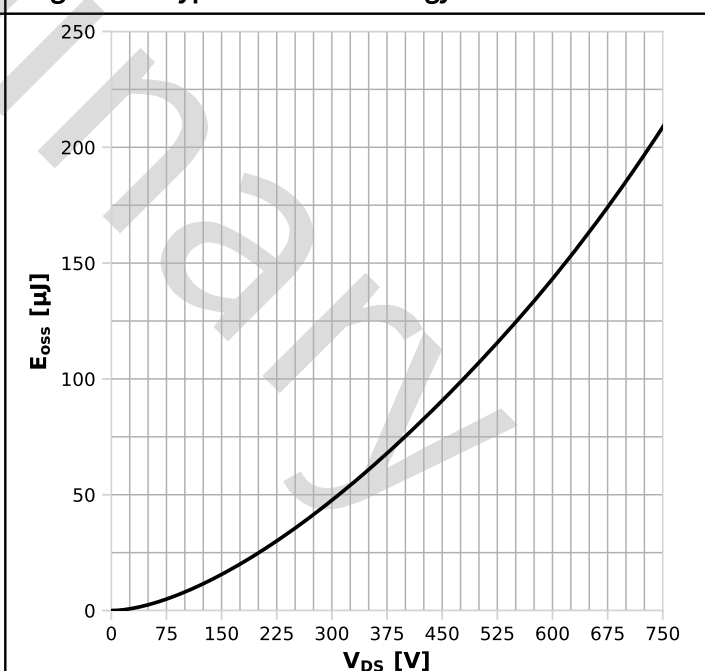
$V_{GS} = f(Q_{gate})$; $I_D = 40.2 \text{ A}$ pulsed; $V_{dr} = -18 \text{ V}$; parameter: V_{DD}

Diagram 11: Typ. capacitances AC



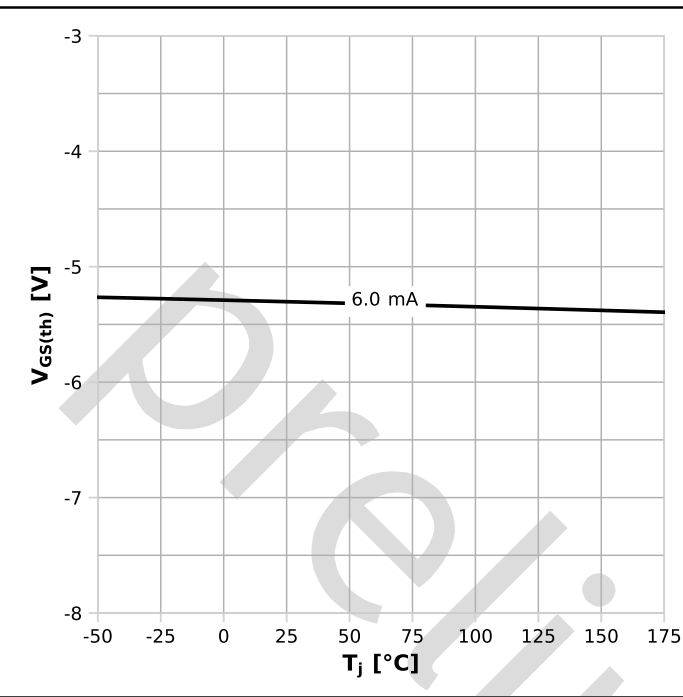
$C = f(V_{DS})$; $V_{GS} = -18 \text{ V}$; $f = 250 \text{ kHz}$

Diagram 12: Typ. Coss stored energy AC



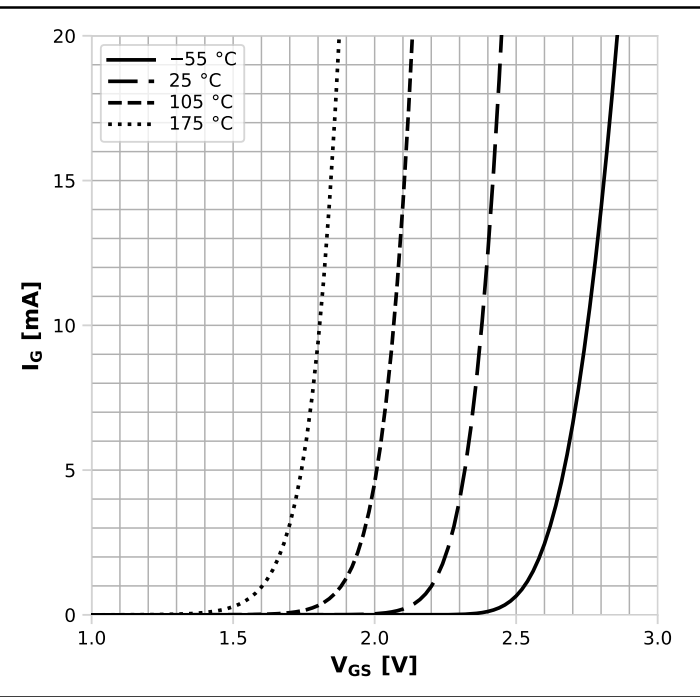
$E_{oss} = f(V_{DS})$; $V_{GS} = -18 \text{ V}$

Diagram 15: Typ. gate threshold voltage



$V_{GS(th)} = f(T_j)$, $V_{DS} = 1$ V; parameter: I_D

Diagram 16: Typ. transfer gate forward current



$I_G = f(V_{GS})$, $V_{DS} = 0$ V; parameter: T_j

5 Test circuits

Table 8 Switching times

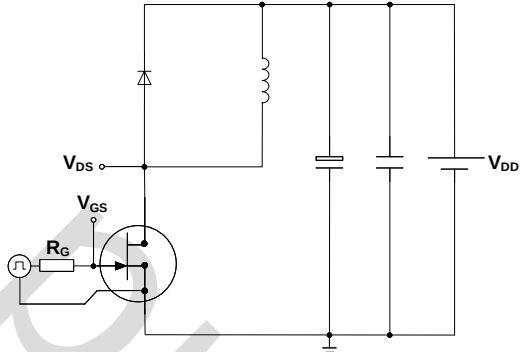
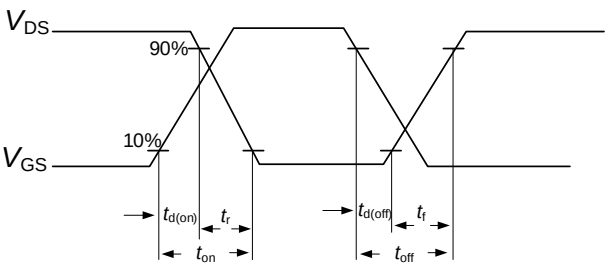
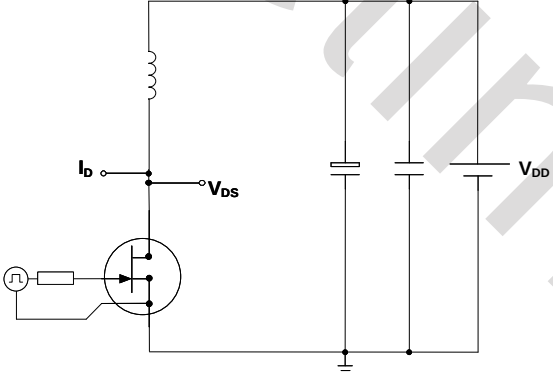
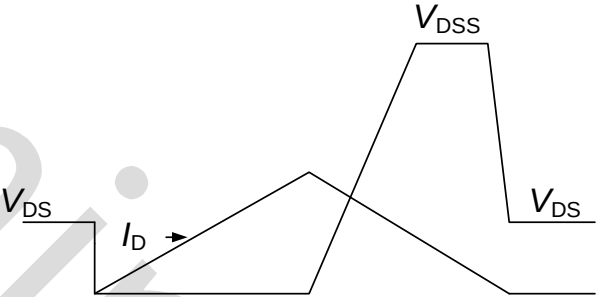
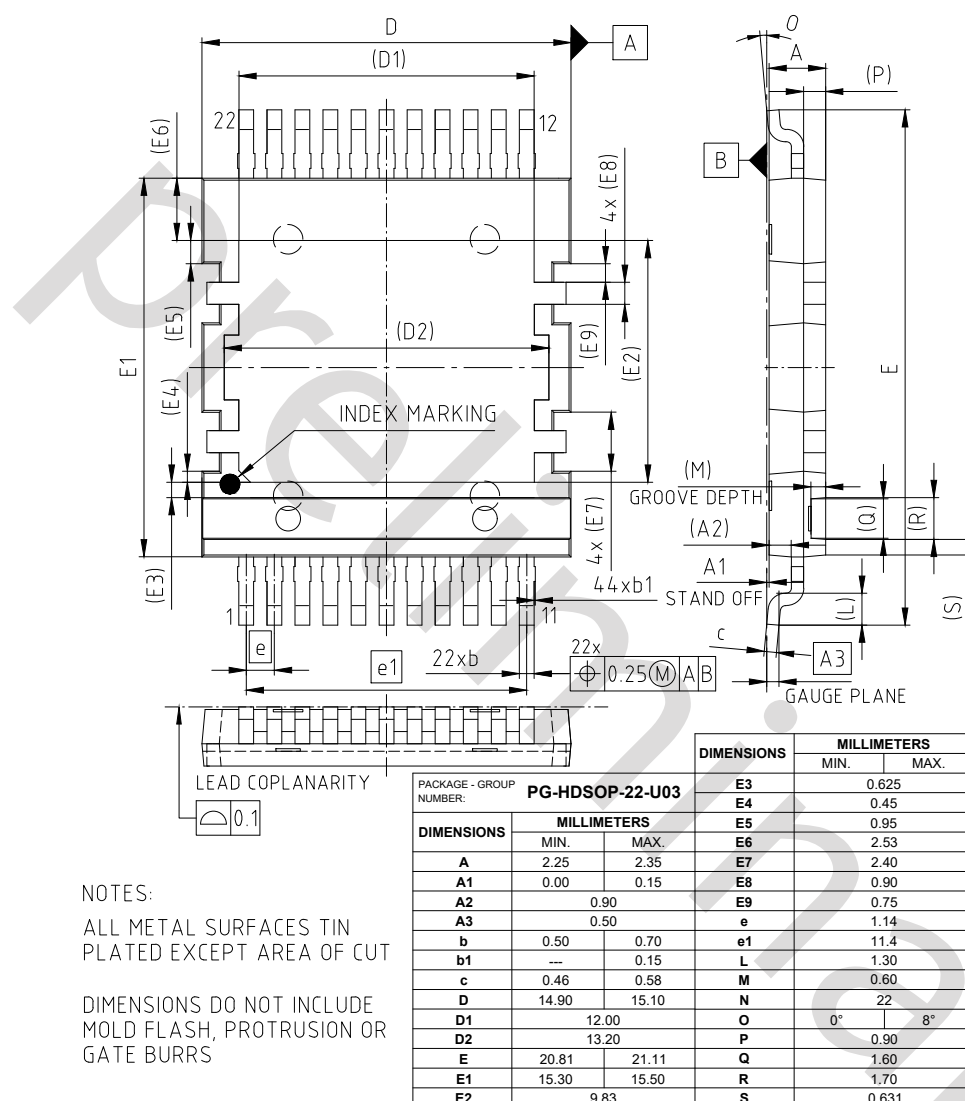
Switching times test circuit for inductive load	Switching times waveform
	

Table 9 Unclamped inductive load

Unclamped inductive load test circuit	Unclamped inductive waveform
	

6 Package outlines



NOTES:
ALL METAL SURFACES TIN
PLATED EXCEPT AREA OF CUT

DIMENSIONS DO NOT INCLUDE
MOLD FLASH, PROTRUSION OR
GATE BURRS

Figure 1 Outline PG-HDSOP-22, dimensions in mm

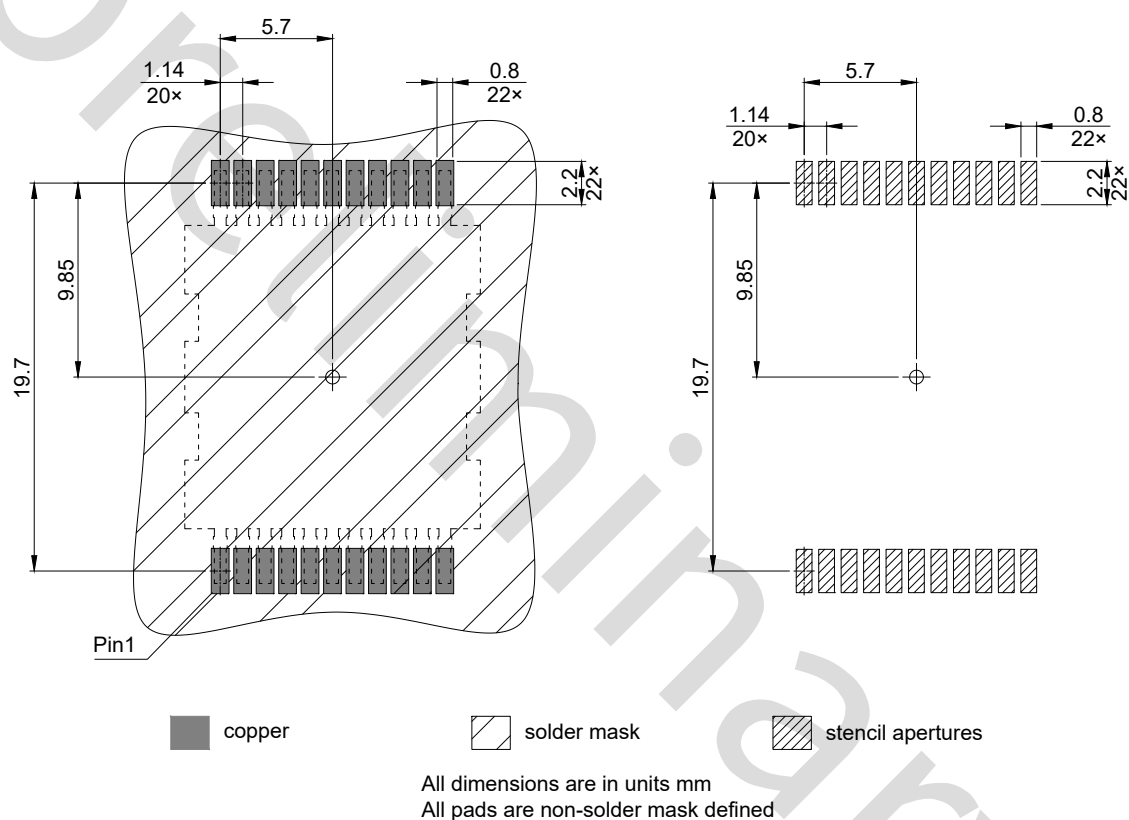


Figure 2 Footprint drawing PG-HDSOP-22, dimensions in mm

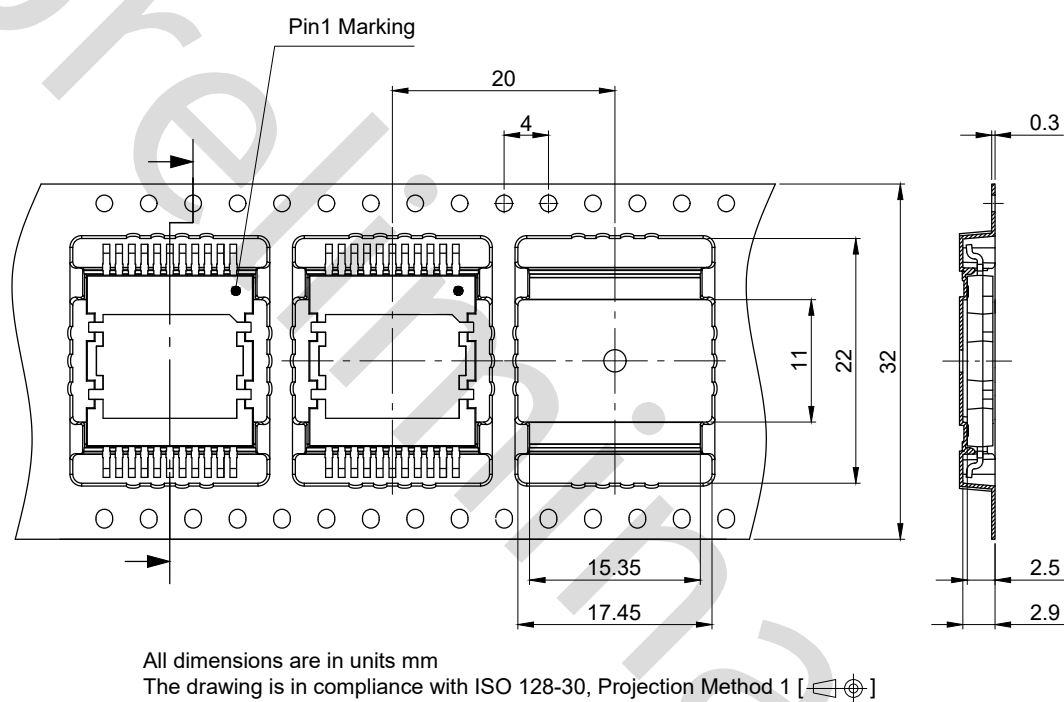


Figure 3 Packaging variant PG-HDSOP-22, dimensions in mm

7 Appendix A

Table 10 **Related links**

- [IFX CoolSiC™ JFET 750 V J1 Webpage](#)
- [IFX CoolSiC™ JFET 750 V J1 Application Note](#)
- [IFX CoolSiC™ JFET 750 V J1 Simulation Model](#)
- [IFX Design tools](#)

Preliminary

Revision history

IJCQ75RM22J1

Revision 2026-05-21, Rev. 0.1

Previous revisions

Revision	Date	Subjects (major changes since last revision)
0.1	2026-05-21	Release of preliminary version

Preliminary

Trademarks

All referenced product or service names and trademarks are the property of their respective owners.

Published by Infineon Technologies AG, Am Campeon 1-15, 85579 Neubiberg, Germany
Copyright (c) 2026 Infineon Technologies AG and its affiliates. All Rights Reserved.

Important notice

The product is not developed and released for series supply by Infineon.

Subject to the development and release of the product for series supply by Infineon, the technical specifications of the product are set forth in the relevant final product data sheet provided by Infineon.

Infineon reserves the right to change all information given in this document at any time without notice.

Products which may also include samples and may be comprised of hardware or software or both ("Product(s)") are sold or provided and delivered by Infineon Technologies AG and its affiliates ("Infineon") subject to the terms and conditions of the frame supply contract or other written agreement(s) executed by a customer and Infineon or, in the absence of the foregoing, the applicable Sales Conditions of Infineon. General terms and conditions of a customer or deviations from applicable Sales Conditions of Infineon shall only be binding for Infineon if and to the extent Infineon has given its express written consent.

For the avoidance of doubt, Infineon disclaims all warranties of non-infringement of third-party rights and implied warranties such as warranties of fitness for a specific use/purpose or merchantability.

Infineon shall not be responsible for any information with respect to samples, the application or customer's specific use of any Product or for any examples or typical values given in this document.

The data contained in this document is exclusively intended for technically qualified and skilled customer representatives. It is the responsibility of the customer to evaluate the suitability of the Product for the intended application and the customer's specific use and to verify all relevant technical data contained in this document in the intended application and the customer's specific use. The customer is responsible for properly designing, programming, and testing the functionality and safety of the intended application, as well as complying with any legal requirements related to its use.

Unless otherwise explicitly approved by Infineon, Products may not be used in any application where a failure of the Products or any consequences of the use thereof can reasonably be expected to result in personal injury. However, the foregoing shall not prevent the customer from using any Product in such fields of use that Infineon has explicitly designed and sold it for, provided that the overall responsibility for the application lies with the customer.

Infineon expressly reserves the right to use its content for commercial text and data mining (TDM) according to applicable laws, e.g. Section 44b of the German Copyright Act (UrhG).

If the Product includes security features: Because no computing device can be absolutely secure, and despite security measures implemented in the Product, Infineon does not guarantee that the Product will be free from intrusion, data theft or loss, or other breaches ("Security Breaches"), and Infineon shall have no liability arising out of any Security Breaches.

If this document includes or references software:

The software is owned by Infineon under the intellectual property laws and treaties of the United States, Germany, and other countries worldwide. All rights reserved. Therefore, you may use the software only as provided in the software license agreement accompanying the software. If no software license agreement applies, Infineon hereby grants you a personal, non-exclusive, non-transferable license (without the right to sublicense) under its intellectual property rights in the software (a) for software provided in source code form, to modify and reproduce the software solely for use with Infineon hardware products, only internally within your organization, and (b) to distribute the software in binary code form externally to end users, solely for use on Infineon hardware products. Any other use, reproduction, modification, translation, or compilation of the software is prohibited.

For further information on the Product, technology, delivery terms and conditions, and prices, please contact your nearest Infineon office or visit <https://www.infineon.com>.